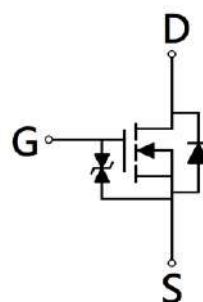
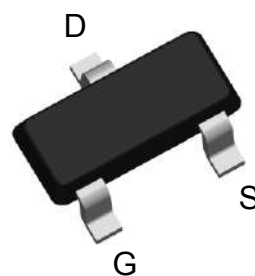


N-Channel Enhancement Mode MOSFET

Features:

- Low On Resistance
- Low Gate Charge
- Fast Switching Characteristic
- ESD protected gate, typical 4kV (HBM)

SOT-523



G : Gate S : Source D : Drain

BV_{DSS}	30V
$I_D @ V_{GS}=4.5V, T_A=25^\circ C$	1A
$R_{DS(ON) typ.} @ V_{GS}=4.5V, I_D=0.2A$	0.5Ω
$R_{DS(ON) typ.} @ V_{GS}=2.5V, I_D=0.2A$	0.6Ω
$R_{DS(ON) typ.} @ V_{GS}=1.8V, I_D=10mA$	0.9Ω

Ordering Information

Device	Package	Shipping
KWA500N03K	SOT-523 (Pb-free lead plating and halogen-free package)	3000 pcs / Tape & Reel

Absolute Maximum Ratings (T_A=25°C)

Parameter	Symbol	Limits	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _{GS}	±8	
Continuous Drain Current @ V _{GS} =4.5V, T _A =25°C	I _D	1	A
Continuous Drain Current @ V _{GS} =4.5V, T _A =70°C		0.8	
Pulsed Drain Current *a	I _{DM}	2.5	
Continuous Body Diode Forward Current @ T _A =25°C	I _S	1	
ESD susceptibility *b	V _{ESD}	4000	V
Total Power Dissipation	P _D	T _A =25°C 1.3	W
		T _A =70°C 0.8	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55~+150	°C

Thermal Data

Parameter	Symbol	Steady State	Unit
Thermal Resistance, Junction-to-ambient	R _{θJA}	96	°C/W

Note:

*a. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C. Ratings are based on low frequency and low duty cycles to keep initial T_J=25°C.

*b. Human body model, 1.5kΩ in series with 100pF.

Electrical Characteristics (T_A=25°C, unless otherwise specified)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV _{DSS}	30	-	-	V	V _{GS} =0V, I _D =-250μA
V _{GS(th)}	0.4	-	1.2		V _{DS} =V _{GS} , I _D =-250μA
G _{FS}	-	0.8	-	S	V _{DS} =5V, I _D =0.2A
I _{GSS}	-	-	±10	μA	V _{GS} =±8V, V _{DS} =0V
I _{DSS}	-	-	1		V _{DS} =24V, V _{GS} =0V
R _{DS(ON)}	-	0.5	0.7	Ω	V _{GS} =4.5V, I _D =0.2A
	-	0.6	0.9		V _{GS} =2.5V, I _D =0.2A
	-	0.9	2		V _{GS} =1.8V, I _D =10mA
Dynamic					
C _{iss}	-	31	-	pF	V _{DS} =15V, V _{GS} =0V, f=1MHz
C _{oss}	-	11	-		
C _{rss}	-	8	-		
Q _g *1, 2	-	0.9	-	nC	V _{DS} =20V, I _D =0.2A, V _{GS} =4.5V
Q _{gs} *1, 2	-	0.2	-		
Q _{gd} *1, 2	-	0.2	-		
t _{d(ON)} *1, 2	-	5.3	-	ns	V _{DS} =15V, I _D =0.2A, V _{GS} =4.5V, R _{GS} =6 Ω
t _r *1, 2	-	16	-		
t _{d(OFF)} *1, 2	-	20	-		
t _f *1, 2	-	18	-		
Source-Drain Diode					
V _{SD} *1	-	0.85	1.2	V	I _S =0.2A, V _{GS} =0V
t _{rr}	-	4.7	-	ns	I _F =0.5A, dI _F /dt=100A/μs
Q _{rr}	-	1.2	-	nC	

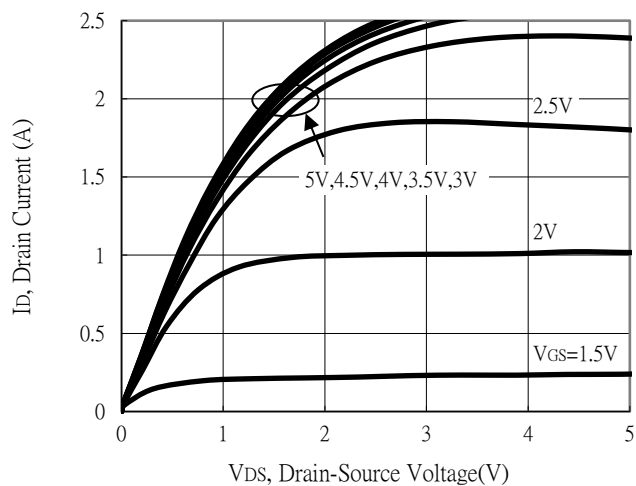
Note:

*1. Pulse Test : Pulse Width ≤300μs, Duty Cycle≤2%

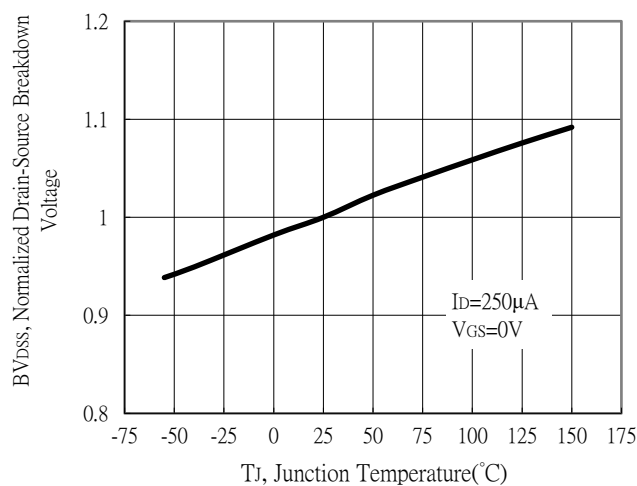
*2. Independent of operating temperature

Typical Characteristics

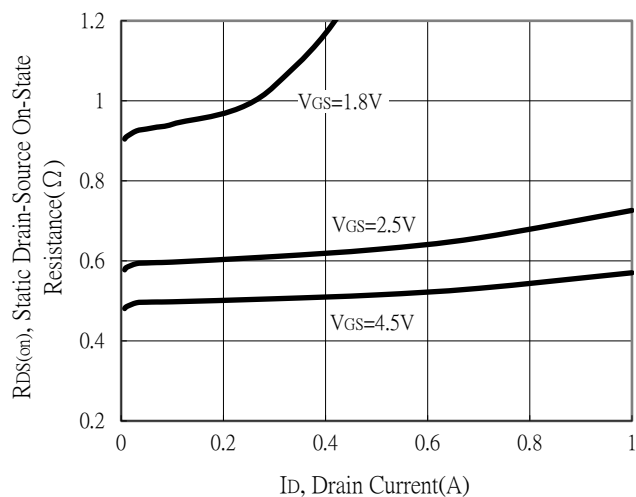
Typical Output Characteristics



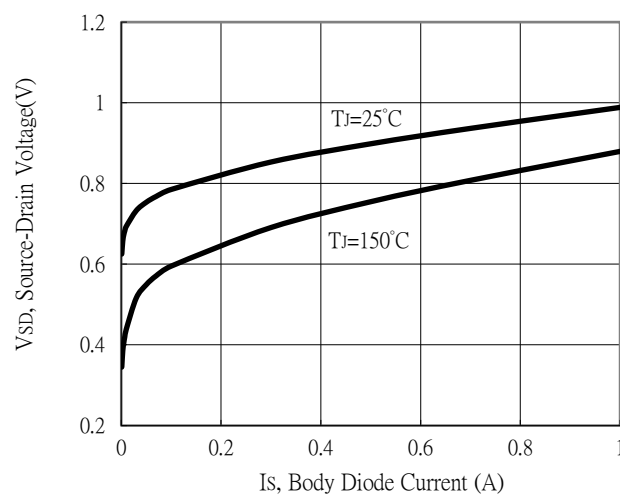
Breakdown Voltage vs Ambient Temperature



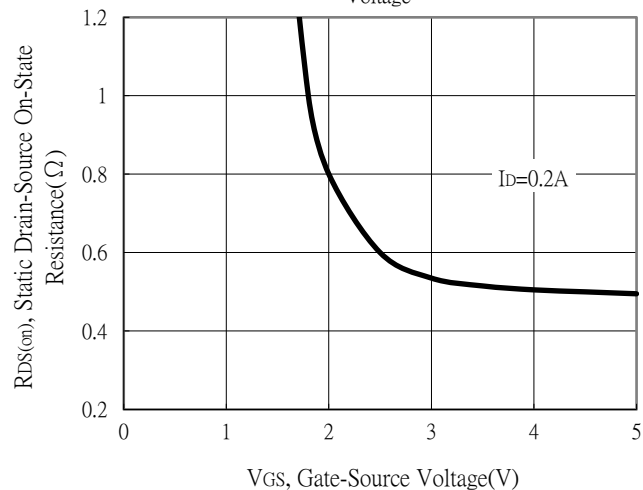
Static Drain-Source On-State resistance vs Drain Current



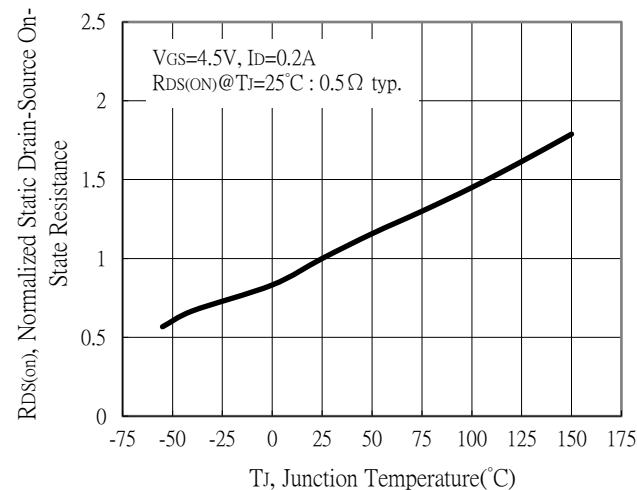
Body Diode Current vs Source-Drain Voltage



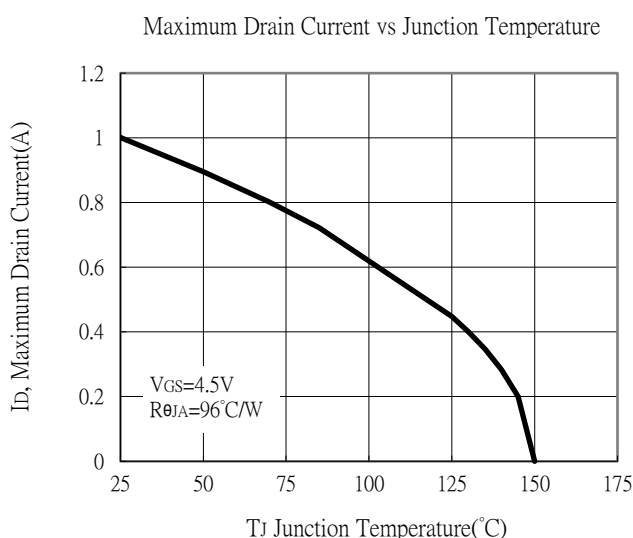
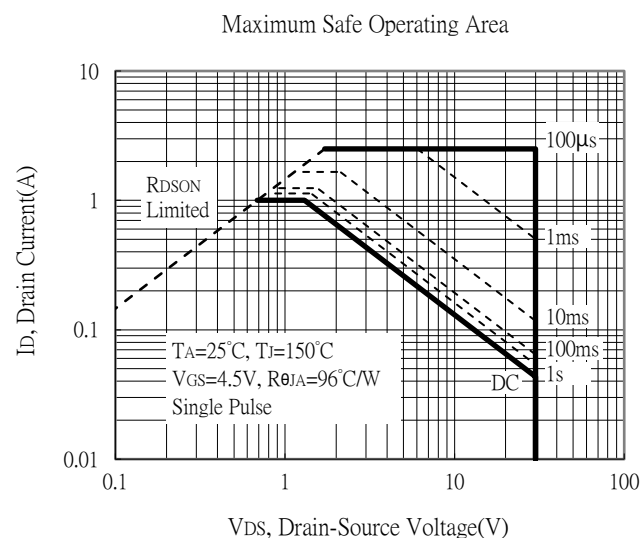
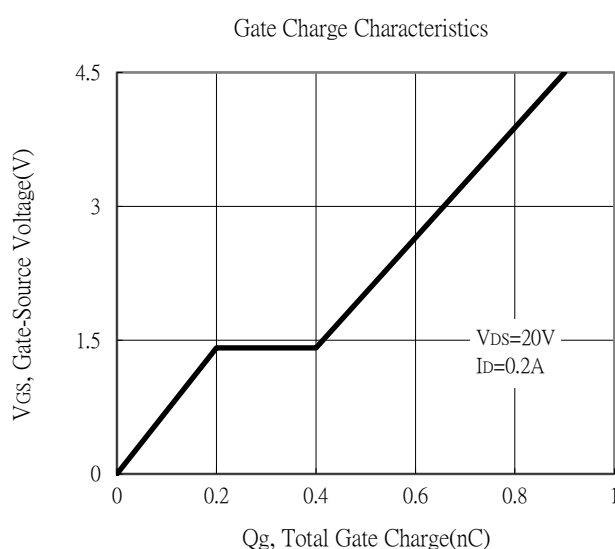
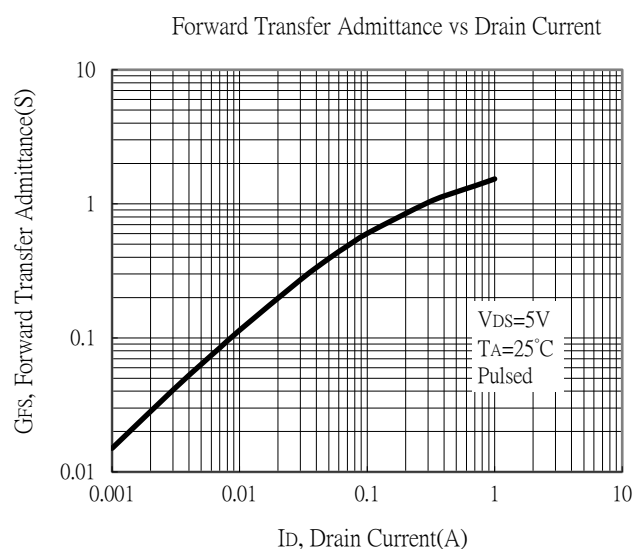
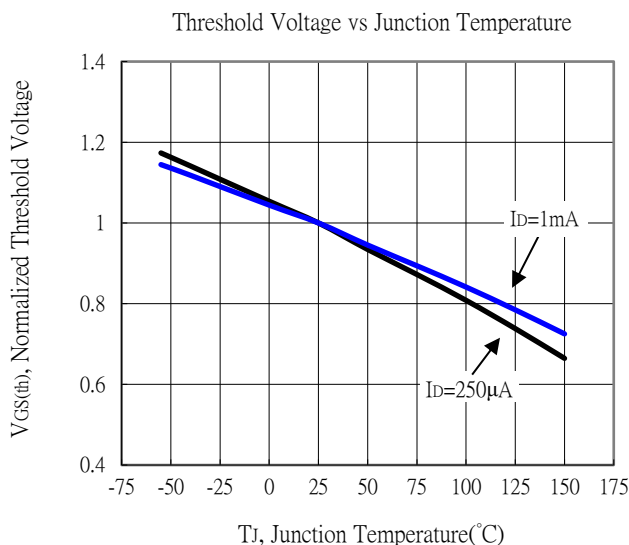
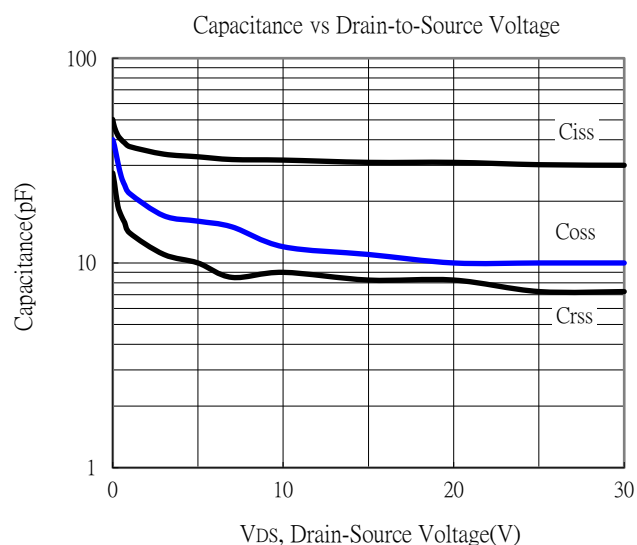
Static Drain-Source On-State Resistance vs Gate-Source Voltage



Drain-Source On-State Resistance vs Junction Temperature

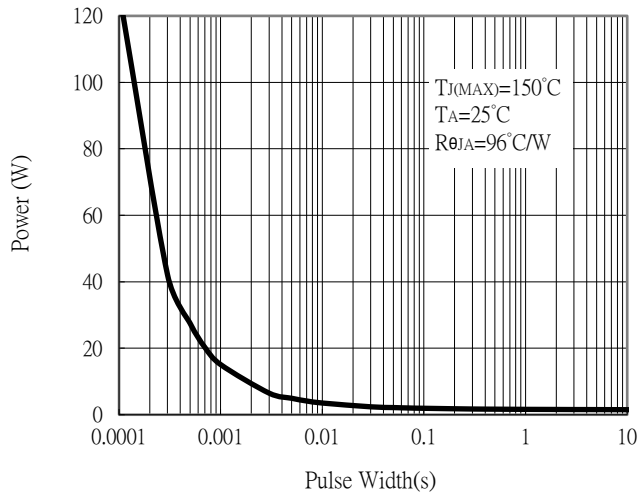


Typical Characteristics (Cont.)

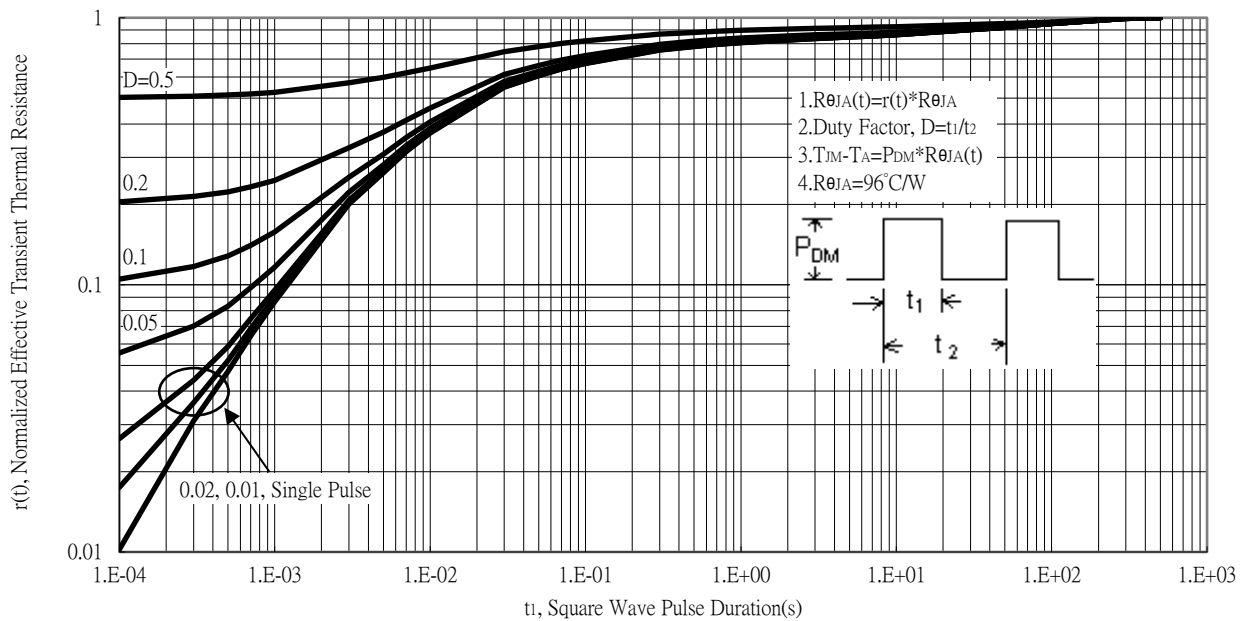


Typical Characteristics (Cont.)

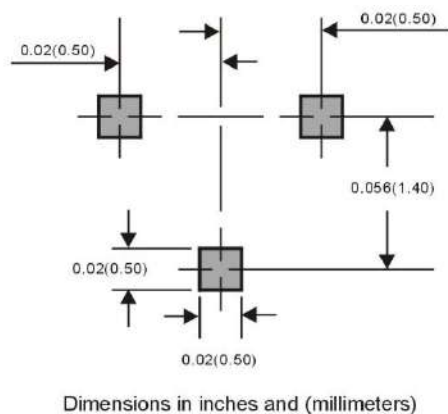
Single Pulse Power Rating, Junction to Ambient



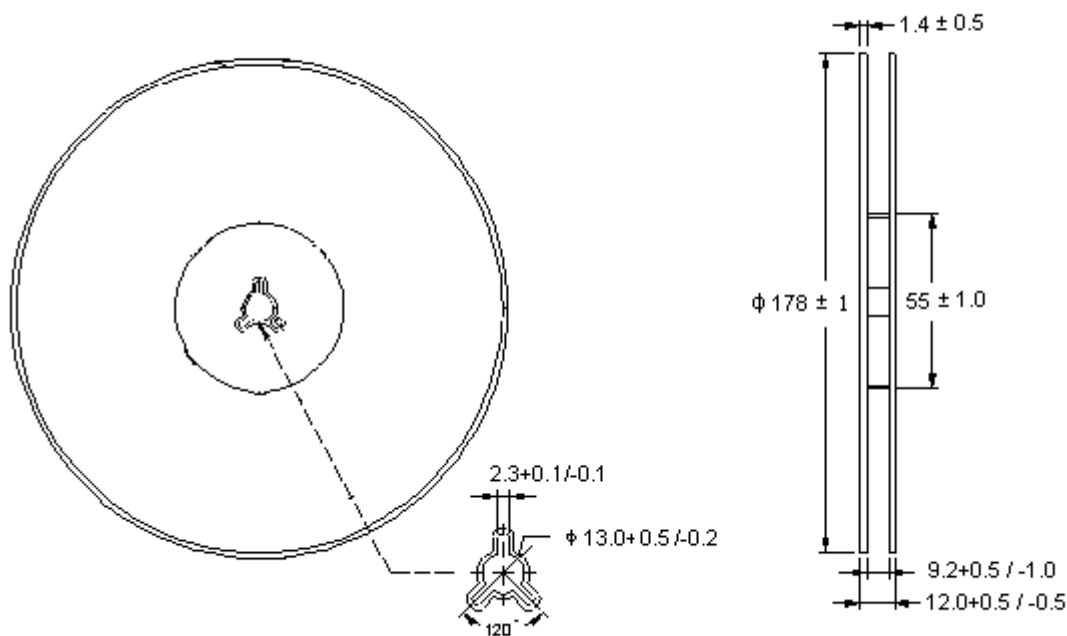
Transient Thermal Response Curves



Recommended Soldering Footprint

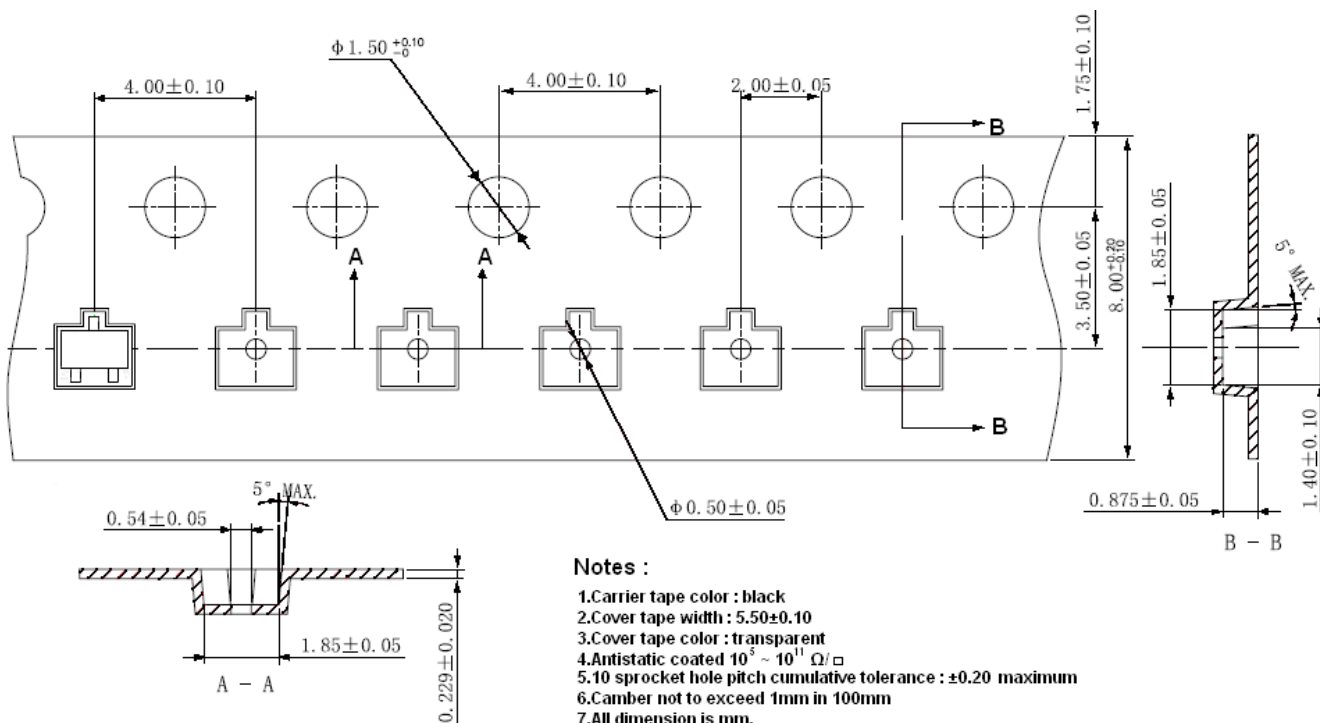


Reel Dimension

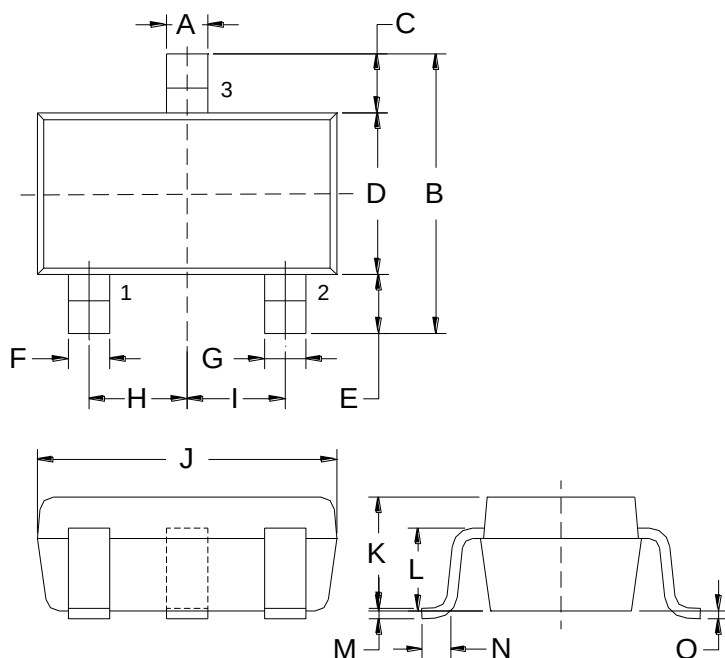


Unit: millimeter

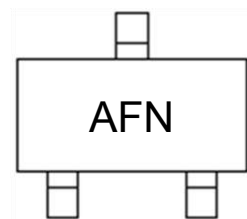
Carrier Tape Dimension



SOT-523 Dimension



Marking:



3-Lead SOT-523 Plastic
Surface Mounted Package

Style: Pin 1.Gate 2.Source 3.Drain

*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0079	0.0157	0.20	0.40	I	*0.0197	-	*0.50	-
B	0.0591	0.0669	1.50	1.70	J	0.0610	0.0650	1.55	1.65
C	0.0118	0.0197	0.30	0.50	K	0.0276	0.0315	0.70	0.80
D	0.0295	0.0335	0.75	0.85	L	0.0224	0.0248	0.57	0.63
E	0.0118	0.0197	0.30	0.50	M	0.0020	0.0059	0.05	0.15
F	0.0039	0.0118	0.10	0.30	N	0.0039	0.0118	0.10	0.30
G	0.0039	0.0118	0.10	0.30	O	0	0.0031	0	0.08
H	*0.0197	-	*0.50	-					